SOD-323

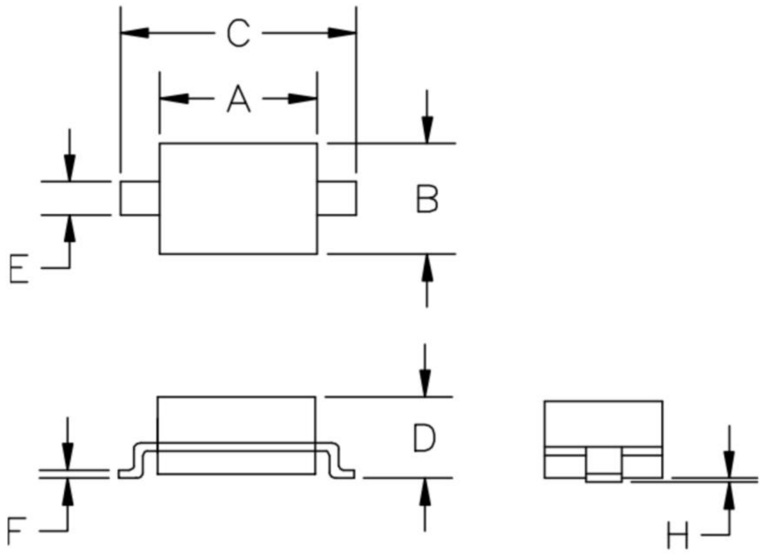
Plastic, surface-mounted package; 2 terminals;
1.7 mm x 1.25 mm x 0.95 mm body
塑料表面贴装封装；2 引脚；
封装本体尺寸 1.7 mm x 1.25 mm x 0.95 mm

1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	SOD-323
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	$1.7mm \times 1.25mm \times 0.95mm$ body 封装本体（不含引脚）尺寸为 $1.7mm \times 1.25mm \times 0.95mm$
Terminals Compliance 引脚合规	2 terminals, Tin Plated Leads, Solderable per MILSTD-202, Method 208 e3 2 个镀锡引脚，可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.005 grams (Approximate) 约 0.005 克

2. Package Outline Dimensions 封装外形尺寸

SOD-323



Symbol 符号	Millimeters 毫米	
	Min.最小值	**Max.最大值**
A	1.500	1.800
B	1.200	1.400
C	2.300	2.700
D	-	1.100
E	0.300	0.400
F	0.100	0.250

3. Suggested Pad Layout 推荐焊盘布局

SOD-323

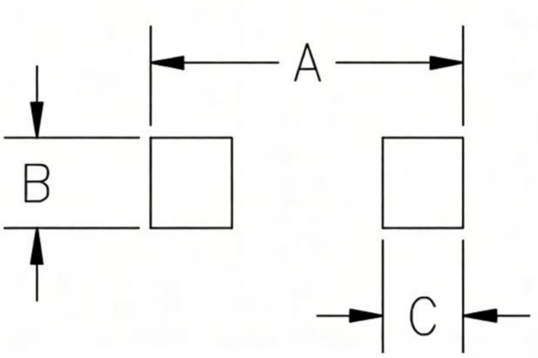


Fig. Soldering footprint for SOD-323

图 SOD-323 的引脚焊接

Dimensions 尺寸	Millimeters 毫米
A	3.15
B	0.80
C	0.80

4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
7	8	3000

Note:

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

说明：上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。

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